California-Pacific-Northwest AI Hardware Hub

Microelectronics Commons

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AI Hardware: 2013 – 2026

Accelerators *vs. general-purpose*

Large one-time benefits

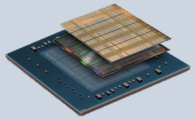
- Arithmetic (e.g., BF16, FP8)
- SIMD
- Systolic arrays
- Custom dataflows

Caution: Excessive customization risky

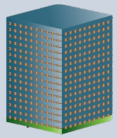
Technology innovations *essential*

Not just advanced nodes

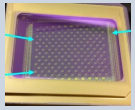
2.5D, 3D



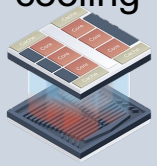
HBM



Optical circuit switch



Microfluidic cooling

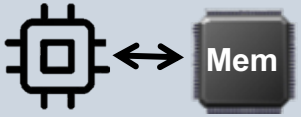


RRAM, MRAM for edge

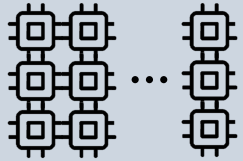
Infineon and TSMC to introduce RRAM

End-to-end systems *crucial*

≠ peak TOPS/W



Off-chip accesses



Many-chip partitioning

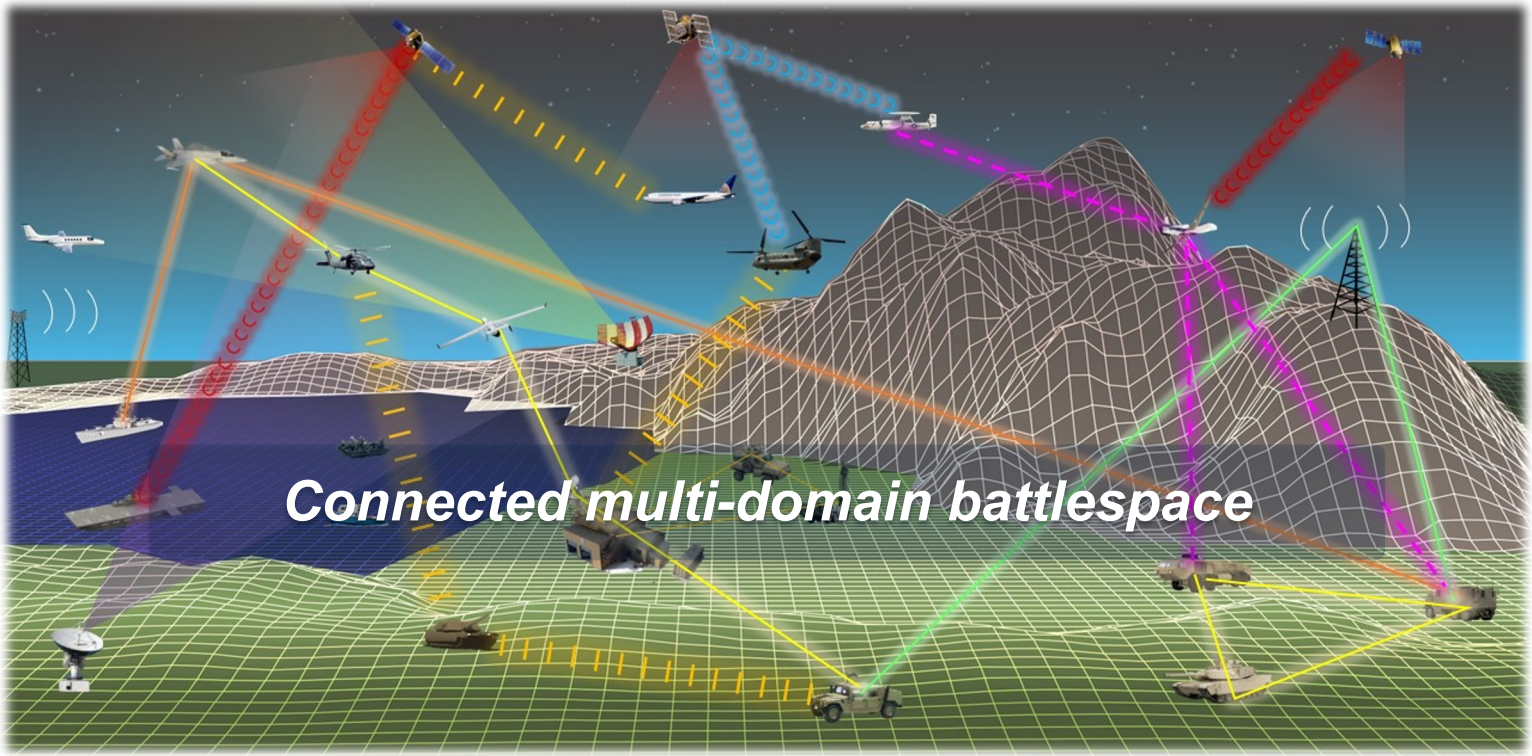
Resilience: silent data corruption

Images from Corintis, Google, Infineon, TSMC, Xilinx, Xperi

BF: Brain Float, FP: Floating Point, SIMD: Single Instruction/Multiple Data, CGRA: Coarse-Grained Reconfigurable Arch, HBM: High-Bandwidth Memory, RRAM: Resistive RAM

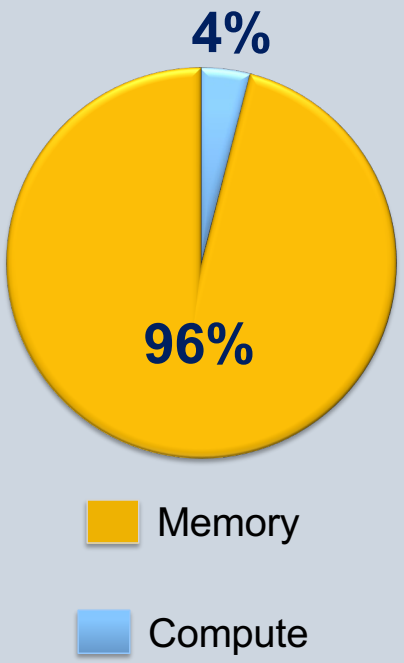
DoD AI: BIG Challenges

Energy & power, real-time, accuracy, continuous learning, harsh (e.g., space)



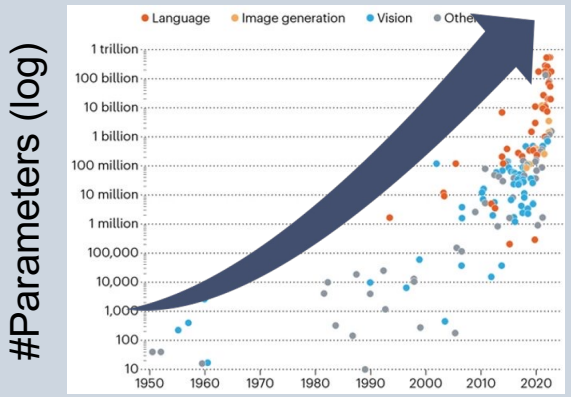
More Challenges Moving Forward

Memory wall



Miniaturization wall

Neural net size explosion



Editorial, Nature, 2023.

More Challenges Moving Forward

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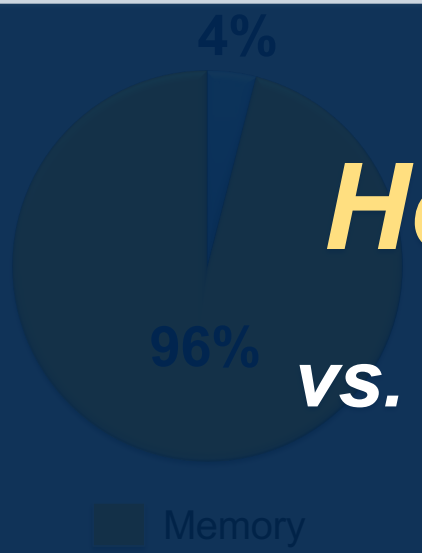
Memory wall

Miniaturization wall

Neural net size explosion

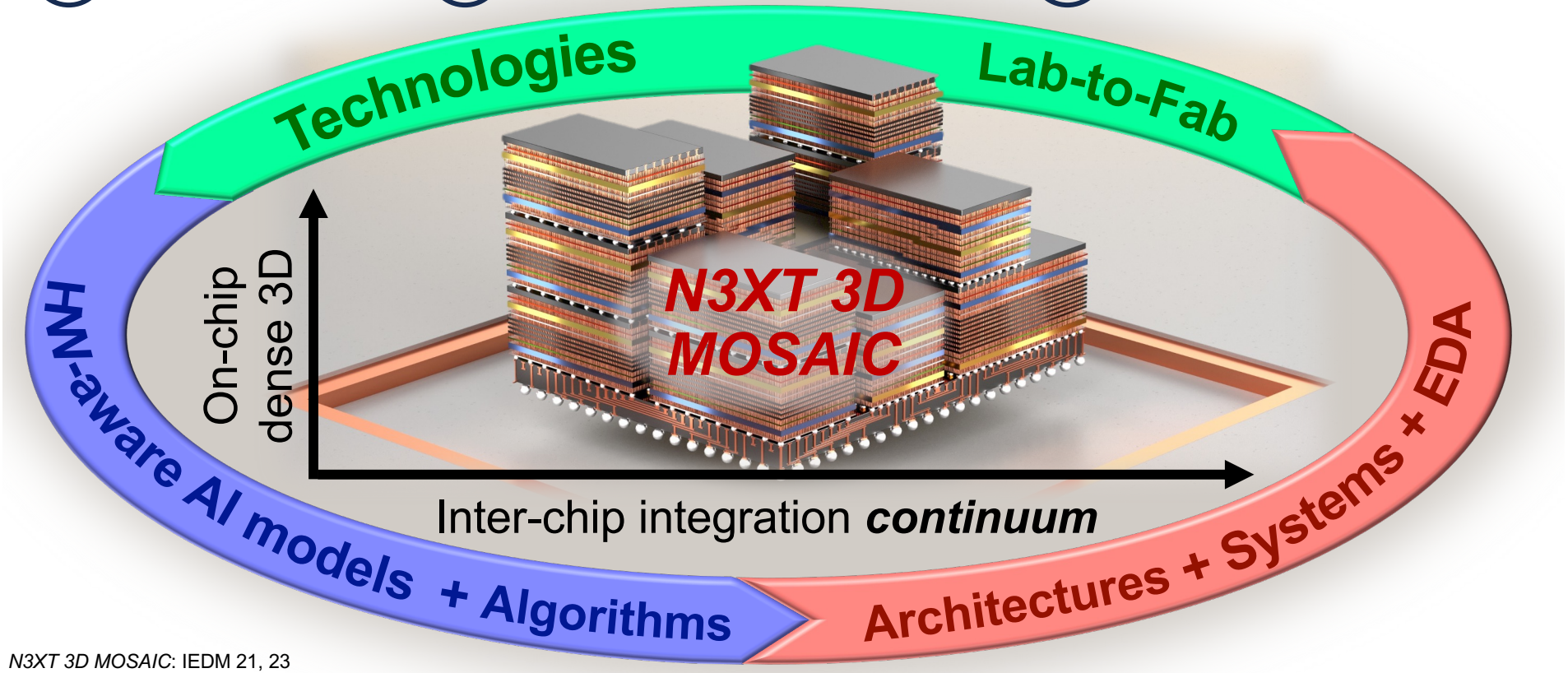


How Next 1,000×?

vs. today's best AI hardware

Our Approach

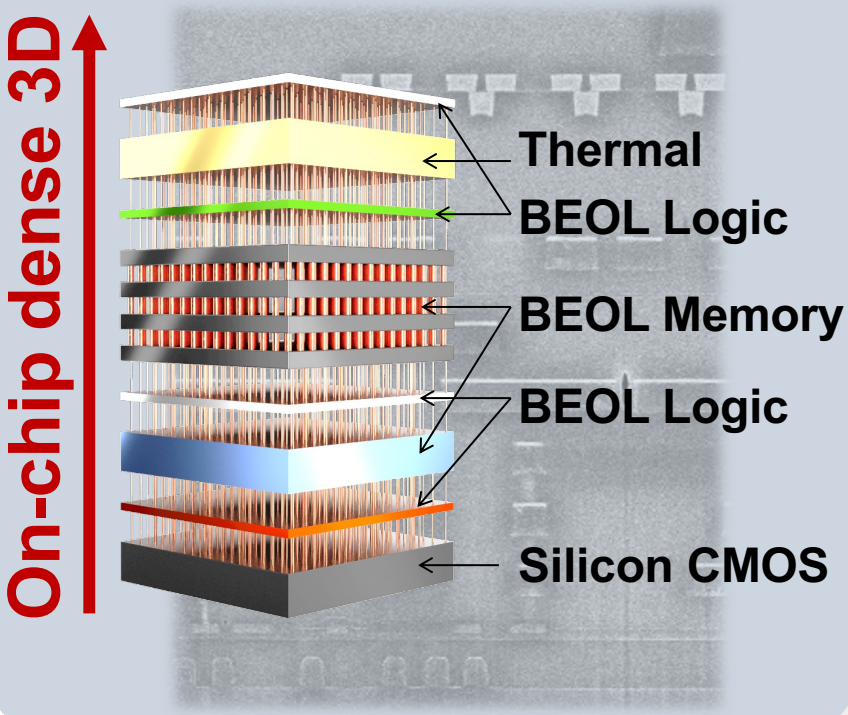
1 Application-driven 2 Diverse & specialized functions 3 Multi-chip 3D NanoSystems



N3XT 3D MOSAIC: IEDM 21, 23

N3XT 3D: Dense 3D & CMOS + X

CMOS + X: Many X's



Lab-to-Fab

ANALOG DEVICES

skywater

Many firsts in industry fabs

- Carbon nanotube FETs (CNFETs)
- Dense monolithic 3D:
  CNFET + RRAM + Si CMOS
- U.S. foundry Resistive RAM (RRAM)

BEOL: Back End of Line

CMOS + X: Many X's

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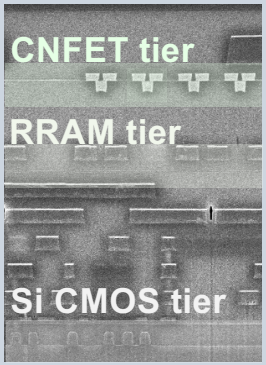
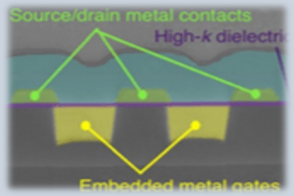
Monolithic 3D



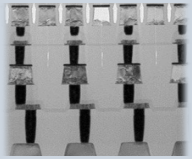
Stanford + MIT + Skywater 23

CNFETs



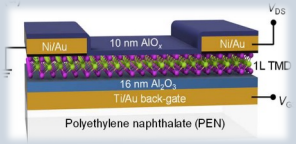
MIT + Skywater 20

Resistive RAM



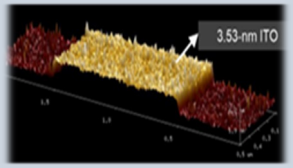
Stanford + SkyWater 21

2D FETs



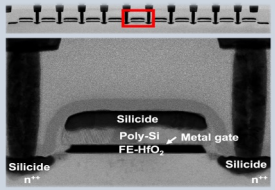
Stanford 23

Oxide FETs



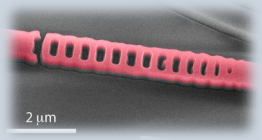
Stanford 23

Ferroelectric FETs



Stanford + GF 23

Inverse-Designed Photonics

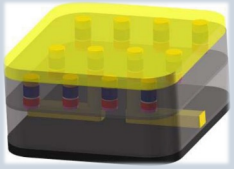


Stanford 22

Codesigned Photonics

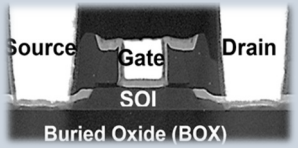
UC Davis 23

Magneto-resistive RAM



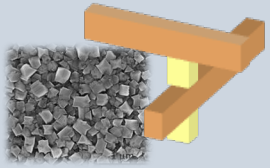
WD 22

NCFETs



Berkeley + MITLL 22

3D Thermal Scaffolding



Stanford 23

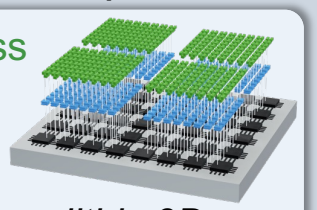
N3XT 3D MOSAIC

Architectures + Systems + EDA

Architectures

Single-chip

CNFET access
RRAM banks
Si compute

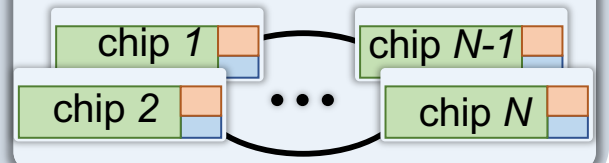


Foundry monolithic 3D:
large EDP benefits

DATE 23, VLSI 23

Multi-chip Illusion

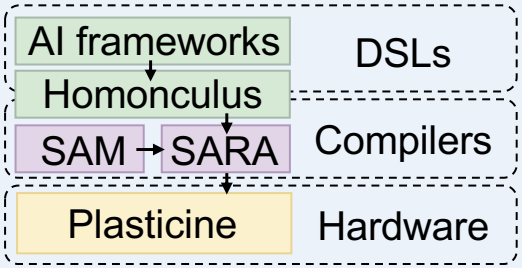
Enough 3D mem. + ***Quick***
ON/OFF = ***Special*** mapping



Nature Electronics 21

Systems

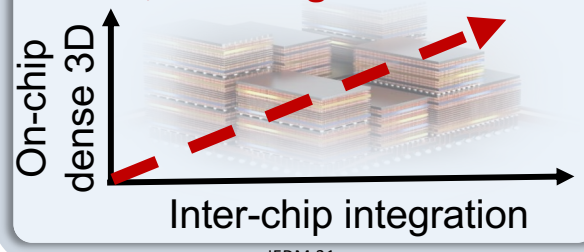
Full-stack dataflow



ASPLOS 23, ISCA 17, 21

Multi-chip Illusion scaleup

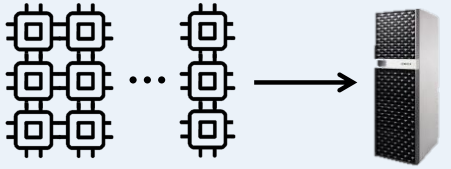
1,000× larger AI models



IEDM 21

EDA

Multi-chip AI systems



partition, map, emulate in mins.
+ 3D thermal, power, noise

Resilience

DATE 08

CNFET: Carbon nanotube FET, RRAM: Resistive RAM, EDP: Energy Delay Product, DSL: Domain-Specific Language

HW-Aware AI Models & Algorithms

New AI algorithms

FlashAttention

I/O-aware Transformer training

- Fast (3×), less mem. (10×)
- Exact attention
- Longer sequences

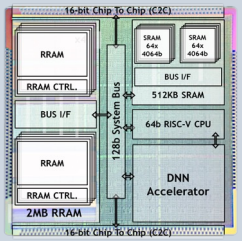
Neural net training theory

Globally optimal training
Quantized activations
Convex optimization

ICLR 23

RRAM-aware training

CHIMERA RRAM Edge AI

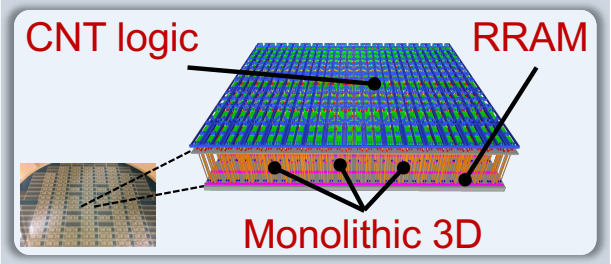


VLSI 21

	vs. SGD
RRAM weight update steps	101× fewer
EDP	340× better
Lifetime (20 images/min)	10 years vs. 2 weeks

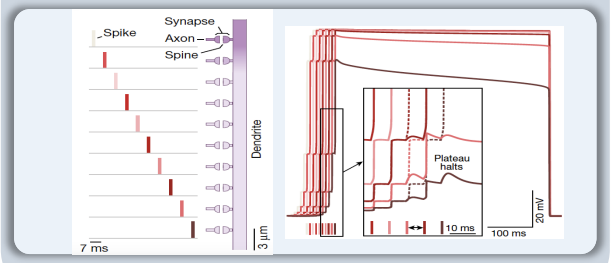
Beyond neural nets

Hyperdimensional



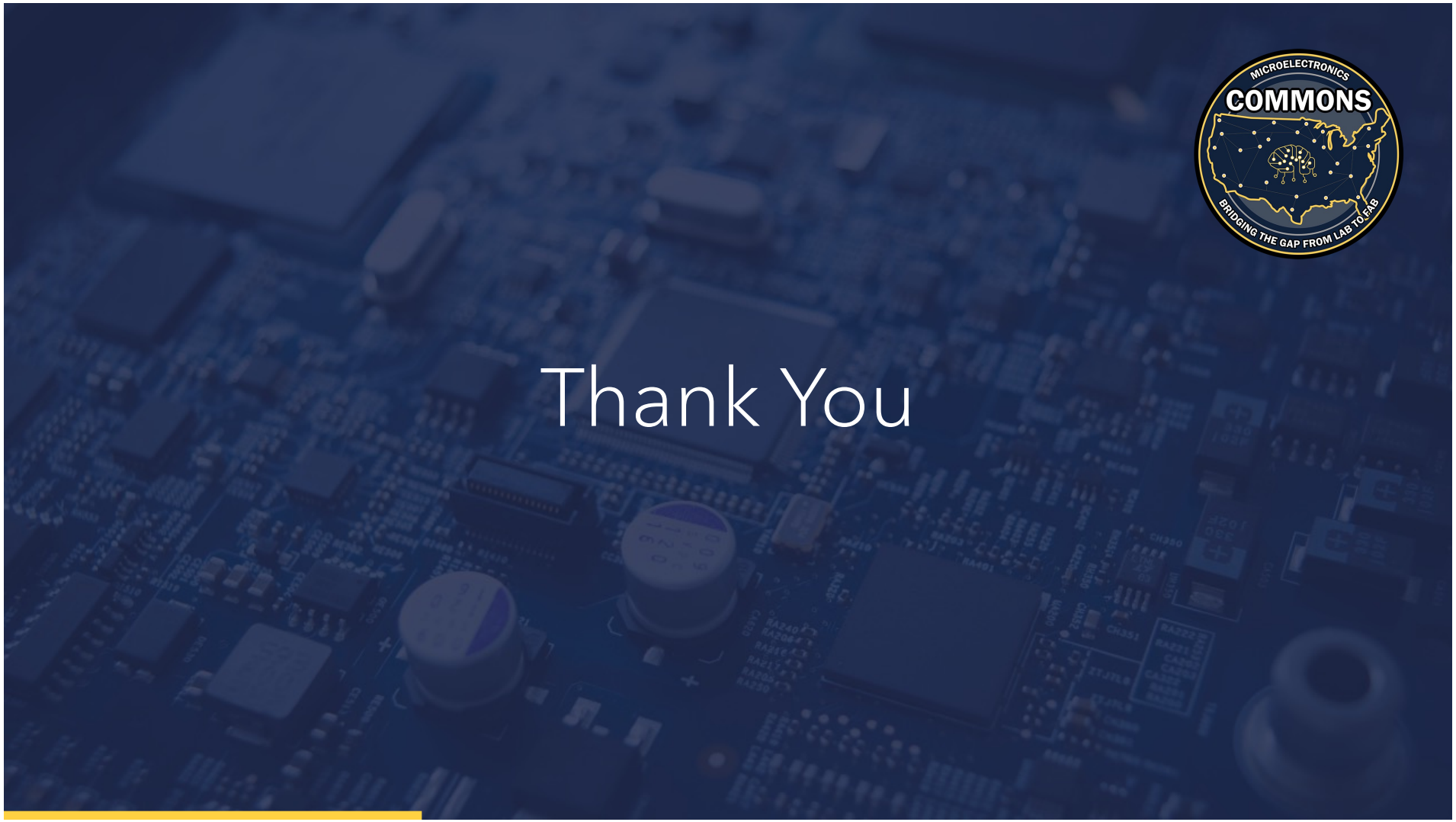
ISSCC 18

Dendritic



Nature 22

RRAM: Resistive RAM, EDP: Energy Delay Product,, SGD: Stochastic Gradient Descent, CNT: Carbon nanotube



Thank You